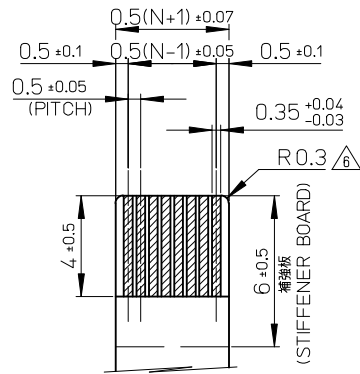


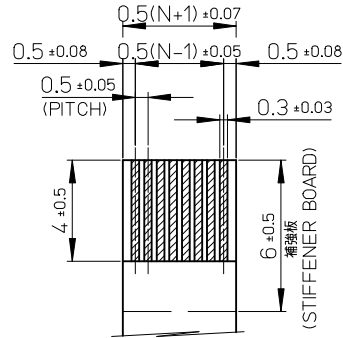
16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
15.1	13.3	9.65	8.5	52745-1890	18
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
13.1	11.3	7.65	6.5	52745-1490	14
12.6	10.8	7.15	6	52745-1390	13
12.1	10.3	6.65	5.5	52745-1290	12
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**17

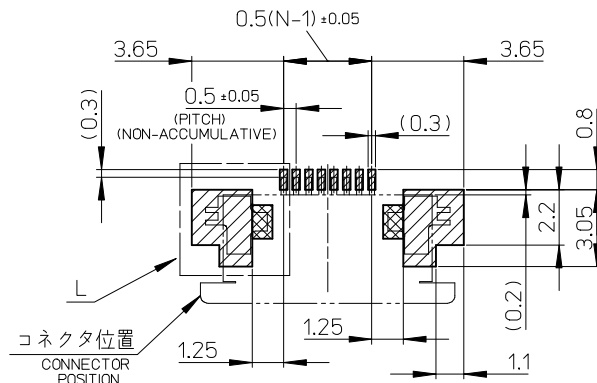
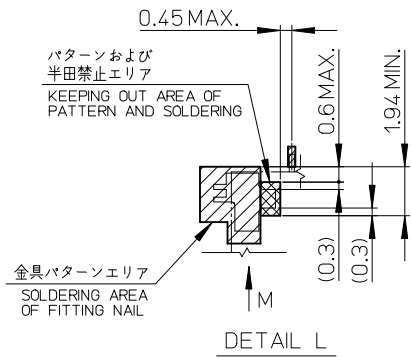
REVISED EC NO: J2014-0207 DRWN: TAKAHASHI 04.2013/07/30 CHKD: TAKAHASHI 2013/10/29 APPR: YNOGAWA 2013/11/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	±0.25	SAIHARA	1994/03/24	0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING						
	30 OVER	±0.3	CHECKED BY	DATE							
ANGULAR ±3 °		SKUNISHI	2000/06/30	molex							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE								
		KMORIKAWA	2010/07/16	SEE CHART		DOCUMENT NO.		SD-52745-054		SHEET NO.	
		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						1 OF 2	



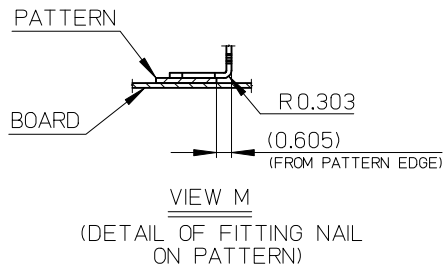
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C. BOARD
 PATTERN DIMENSION(REF.)
 (MOUNTING SIDE)



注記NOTES

1. 使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル: リン青銅、銅下地半田めっき (t=0.2)
 TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
 金具: リン青銅、銅下地半田めっき (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED.
 △3 ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.
 UPPER DIRECTION: 0.1MAXIMUM
 LOWER DIRECTION: 0.15 MAXIMUM

△4 偶数極に適用

APPLY FOR EVEN CIRCUIT.

△5 ハ' ターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

△6 R0.3は、FPCの胴体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。
 補強フィルム材質はポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
 RECOMMENDED MATERIAL :
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING BONDING AGENT

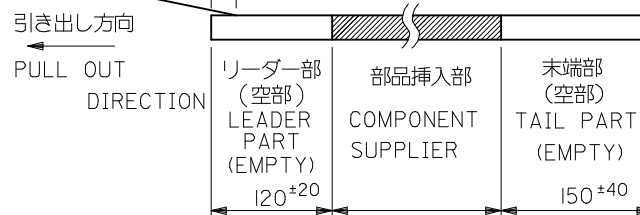
REVISED EC NO: J2014-0207 DRWN: MTAHASHI 04.2013/07/30 CHKD: KAKAHASHI 2013/10/29 APPR: YNOGAWA 2013/11/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING			
		10 OVER 30 UNDER	± ---	CHECKED BY SKUNISHI	DATE 2000/06/30				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/07/16				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1 OF 2		DOCUMENT NO. SD-52745-054		SHEET NO. 2 OF 2	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記 NOTES

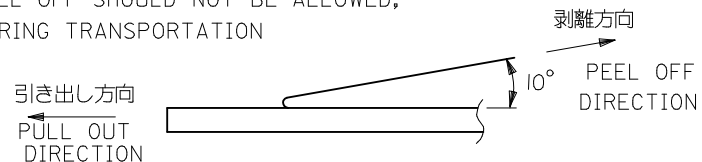
1. 製品番号 52745-**17 の梱包状態はアクチュエータがロックした状態とする。
 詳細寸法については図面 SD-52745-054 を参照下さい。
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED
 RE DETAILED DIMENSIONS,SEE SD-52745-054

2. 梱包数量：1000個/リール
 NUMBER OF CONNECTORS:1000PCS/REEL

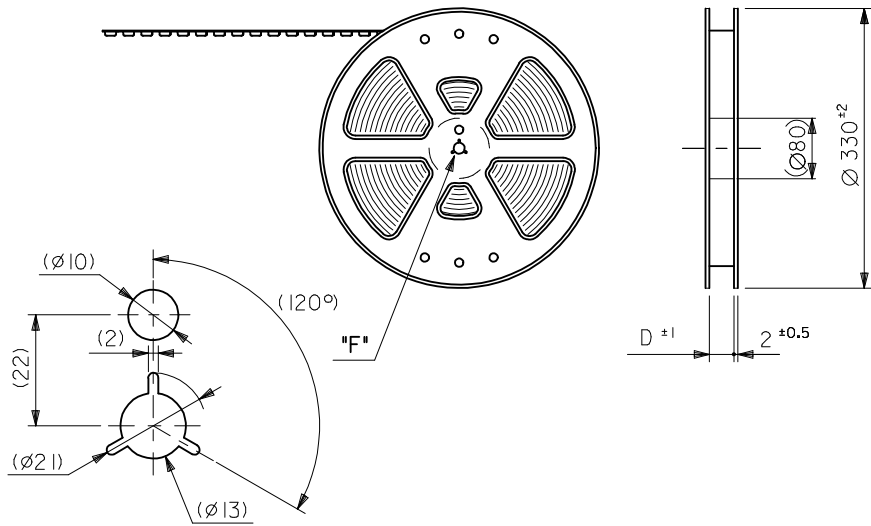
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)
 PEELING OFF FORCE OF TOP TAPE
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION



引き出し方向
 PULL OUT
 DIRECTION

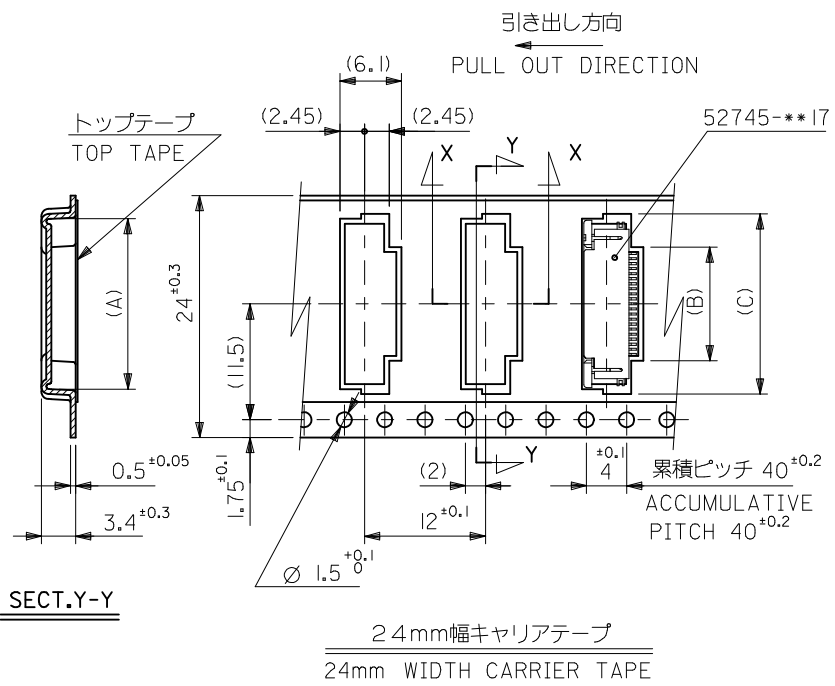


DETAIL "F"

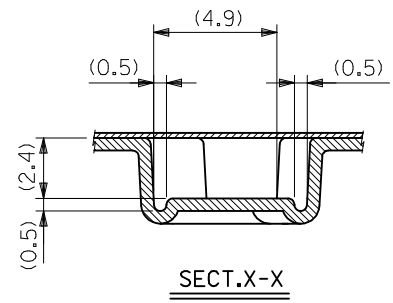
5. 材料 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYREN(PS)
 <RECYCLE MATERIAL CONTAINED>

RELEASED EC NO: J2014-0207 DRWN:MTAKAHASHI 04.2013/07/30 CHKD:KTAKAHASHI 2013/10/29 APPR:YNOGAWA 2013/11/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY MTAKAHASHI	DATE 04.2013/07/30	TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (1/3)		
	10 OVER 30 UNDER	±---	CHECKED BY KTAKAHASHI	DATE 2013/07/30			
	30 OVER	±---	APPROVED BY YNOGAWA	DATE 2013/11/07			
ANGULAR	±---°	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE CHART		SD-52745-057		1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

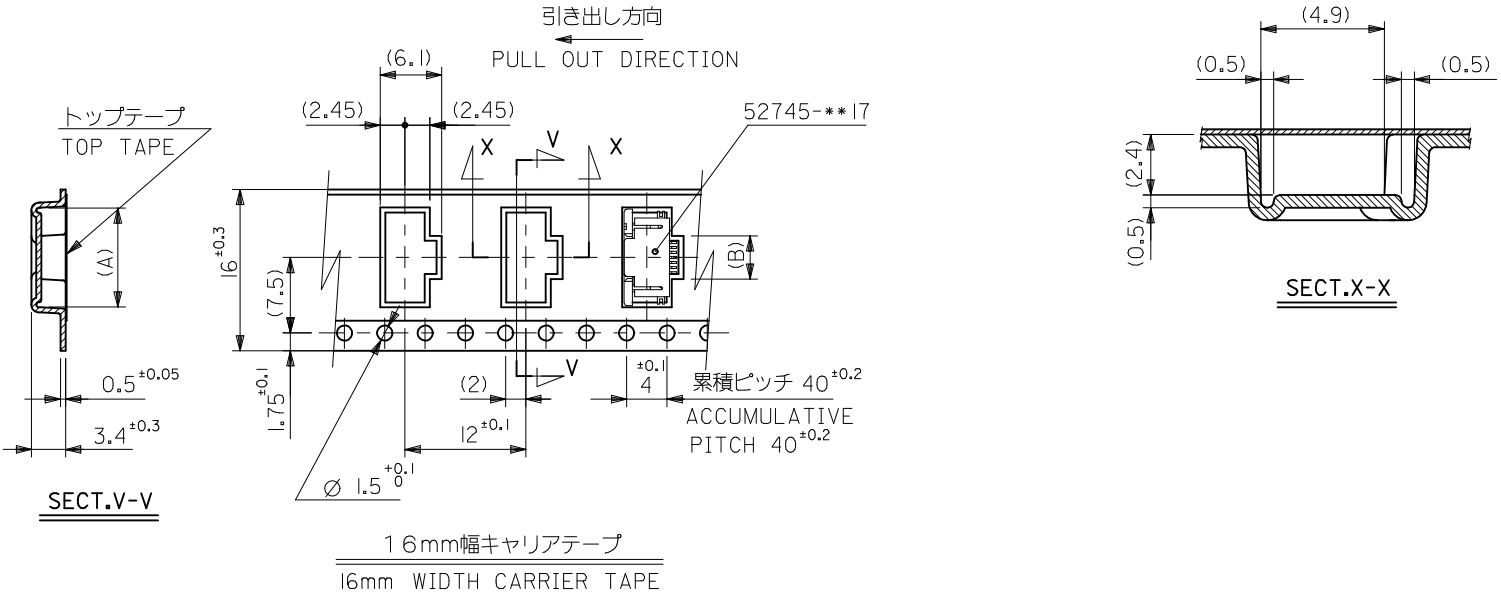


SECT.Y-Y



24	25.5	17.4	10.8	16.4	52745-2090	20
		16.9	10.3	15.9	-1990	19
		16.4	9.8	15.4	-1890	18
		15.4	8.8	14.4	-1690	16
		14.9	8.3	13.9	-1590	15
		14.4	7.8	13.4	-1490	14
		13.9	7.3	12.9	-1390	13
		13.4	6.8	12.4	-1290	12
		12.9	6.3	11.9	-1190	11
		12.4	5.8	11.4	-1090	10
		11.9	5.3	10.9	-0990	9
		11.4	4.8	10.4	-0890	8
10.9	4.3	9.9	-0790	7		
10.4	3.8	9.4	52745-0690	6		
キャリアテープ幅 CARRIER TAPE IDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CIRCUIT

RELEASED EC NO: J2014-0207 DRWN:MTAKAHASHI 04.2013/07/30 CHKD:KTAKAHASHI 2013/10/29 APPR:YNOGAWA 2013/11/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	REV	10 UNDER	±---	DRAWN BY MTAKAHASHI 04	DATE 2013/07/30	TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (2/3)
		10 OVER 30 UNDER	±---	CHECKED BY KTAKAHASHI	DATE 2013/07/30	molex DOCUMENT NO. SD-52745-057 SHEET NO. 2 OF 3
		30 OVER	±---	APPROVED BY YNOGAWA	DATE 2013/11/07	
		ANGULAR	±---°	MATERIAL NO.	SEE CHART	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

RELEASED EC NO: J2014-0207 DRWN: MTAKAHASHI 04 2013/07/30 CHKD: KTAKAHASHI 2013/10/29 APPR: YNOGAWA 2013/11/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	---	METRIC	
	10 UNDER ± --- 10 OVER 30 UNDER ± --- 30 OVER ± --- ANGULAR ± --- °		DRAWN BY: MTAKAHASHI 04 DATE: 2013/07/30 CHECKED BY: KTAKAHASHI DATE: 2013/07/30 APPROVED BY: YNOGAWA DATE: 2013/11/07	TITLE		0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (3/3)
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MATERIAL NO. DOCUMENT NO. SD-52745-057	

